

STRUCTURE	Silicon Monolithic Integrated Circuit
TYPE	Step down DC/DC converter Controller IC for NOTE PC
PRODUCT SERIES	<b>BD95371MUV</b>
FEATURES	<ul style="list-style-type: none"> <li>• Built in H<sup>3</sup>Reg DC/DC controller</li> <li>• Switching Frequency Variable (f=200kHz~500kHz)</li> </ul>

○ ABSOLUTE MAXIMUM RATINGS (Ta=25°C)

Parameter	Symbol	Limit	Unit
Input Voltage 1	VCC	7 *1*2	V
Input Voltage 2	VDD	7 *1*2	V
Input Voltage 3	VIN	28 *1*2	V
BOOT Voltage	BOOT	35 *1*2	V
BOOT-SW Voltage	BOOT-SW	7 *1*2	V
HG-SW Voltage	HG-SW	7 *1*2	V
LG Voltage	LG	VDD	V
Output Voltage	VOUT/Is+/Is-	VCC	V
EN Input Voltage	EN	7 *1	V
Power Dissipation 1	Pd1	0.34*3	W
Power Dissipation 2	Pd2	0.70*4	W
Power Dissipation 3	Pd3	2.20*5	W
Power Dissipation 4	Pd4	3.56*6	W
Operating Temperature Range	Topr	-10~+100	°C
Storage Temperature Range	Tstg	-55~+150	°C
Maximum Junction Temperature	Tjmax	+150	°C

\*1 Not to exceed Pd.

\*2 Instantaneous surge voltage, back electromotive force and voltage under less than 10% duty cycle.

\*3 Reduced by 2.7mW/°C for each increase in Ta of 1°C over 25°C. (when don't mounted on a heat radiation board )

\*4 Reduced by 5.6mW/°C for increase in Ta of 1°C over 25°C. (when mounted on a board 70.0mm×70.0mm×1.6mm 1-layer Glass-epoxy PCB, copper foil area: 10.29mm<sup>2</sup>)

\*5 Reduced by 17.6mW/°C for increase in Ta of 1°C over 25°C. (when mounted on a board 70.0mm×70.0mm×1.6mm 4-layer Glass-epoxy PCB, copper foil area: 10.29mm<sup>2</sup> 2,3-layer copper foil area: 5505mm<sup>2</sup>)

\*6 Reduced by 28.5mW/°C for increase in Ta of 1°C over 25°C. (when mounted on a board 70.0mm×70.0mm×1.6mm 4-layer Glass-epoxy PCB, copper foil area: 5505mm<sup>2</sup>)

○ OPERATING CONDITIONS (Ta=25°C)

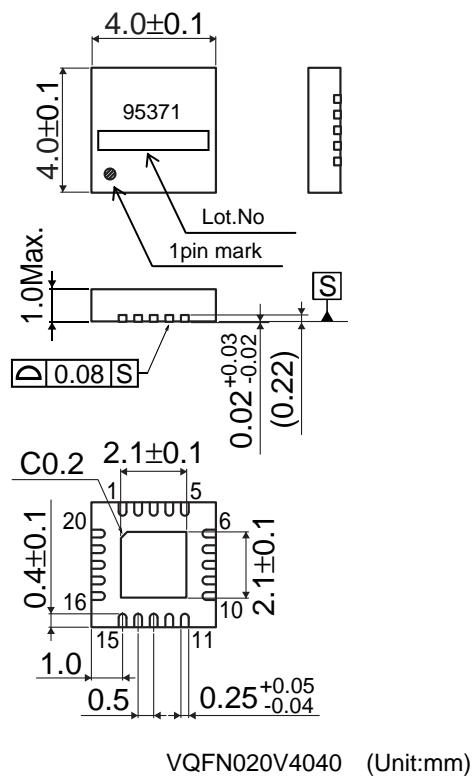
Parameter	Symbol	MIN	MAX	Unit
Input Voltage 1	VCC	4.5	5.5	V
Input Voltage 2	VDD	4.5	5.5	V
Input Voltage 3	VIN	4.5	25	V
BOOT Voltage	BOOT	4.5	30	V
SW Voltage	SW	-0.7	25	V
BOOT-SW Voltage	BOOT-SW	4.5	5.5	V
EN Input Voltage	EN	0	5.5	V
Is Input Voltage	Is+/Is-	0.7	2.7	V
MIN ON Time	Tonmin	-	80	ns

★ This product is not designed for protection against radioactive rays.

○ELECTRICAL CHARACTERISTICS (unless otherwise noted,  $T_a=25^\circ C$ ,  $V_{CC}=5V$ ,  $V_{DD}=5V$ ,  $EN=3V$ ,  $V_{IN}=12V$ ,  $V_{OUT}=1.05V$ ,  $R_{FS}=36k\Omega$ )

Parameter	Symbol	Standard Value			Unit	Condition
		MIN	TYP	MAX		
<b>[Whole Device]</b>						
VCC Bias Current	I <sub>CC</sub>	-	1500	1800	$\mu A$	
VCC Standby Current	I <sub>CCSTB</sub>	-	0	10	$\mu A$	EN=0V
VIN Bias Current	I <sub>IN</sub>	-	30	80	$\mu A$	
VIN Standby Current	I <sub>INSTB</sub>	-	0	10	$\mu A$	EN=0V
EN Low Voltage	V <sub>EN_low</sub>	GND	-	0.8	V	
EN HighVoltage (Forced Continuous mode)	V <sub>ENth_con</sub>	2.3	-	3.8	V	
EN HighVoltage (SLLM Mode)	V <sub>ENth_sllm</sub>	4.5	-	5.5	V	
EN Bias Current	I <sub>EN</sub>	-	15	25	$\mu A$	EN=3V
<b>[Under Voltage Locked Out]</b>						
VCC threshold voltage	V <sub>CC_UVLO</sub>	3.7	4.0	4.3	V	V <sub>CC</sub> : Sweep up
VCC hysteresis voltage	dV <sub>CC_UVLO</sub>	100	160	220	mV	V <sub>CC</sub> : Sweep down
<b>[H<sup>3</sup>REG Control]</b>						
ON Time	T <sub>ON</sub>	194	219	244	ns	
MAX ON Time	T <sub>ONmax</sub>	-	3.5	-	$\mu s$	
MIN OFF Time	T <sub>OFFmin</sub>	-	490	700	ns	
<b>[FET Driver]</b>						
HG Higher side ON resistor	H <sub>GON</sub>	-	3.0	6.0	$\Omega$	
HG Lower side ON resistor	H <sub>GLON</sub>	-	2.0	4.0	$\Omega$	
LG Higher side ON resistor	L <sub>GON</sub>	-	3.0	6.0	$\Omega$	
LG Lower side ON resistor	L <sub>GLON</sub>	-	0.5	1.0	$\Omega$	
<b>[SCP]</b>						
SCP start-up Voltage	V <sub>SCP</sub>	0.345	0.420	0.495	V	
SCP delay time	T <sub>SCP</sub>	-	2.5	-	ms	
<b>[OVP]</b>						
FB threshold voltage	V <sub>OVP</sub>	0.825	0.900	0.975	V	
<b>[Soft start]</b>						
Charge current	I <sub>SS</sub>	1	2	3	$\mu A$	
Standby voltage	V <sub>SS_stb</sub>	-	-	50	mV	
<b>[Current Limit Block]</b>						
Setting Current	I <sub>ILIM</sub>	-	10	-	$\mu A$	
Current limit threshold	I <sub>ILIM</sub>	75	100	125	mV	R <sub>ILIM</sub> =100k $\Omega$
<b>[Output Voltage setting]</b>						
V <sub>OUT</sub> typical voltage	REF	0.743	0.750	0.757	V	
I <sub>S+</sub> Input current	I <sub>IS+</sub>	-1	0	1	$\mu A$	I <sub>S+</sub> =1.05V
I <sub>S-</sub> Input current	I <sub>IS-</sub>	-1	0	1	$\mu A$	I <sub>S-</sub> =-1.05V
<b>[Power Good]</b>						
FB Power Good	V <sub>PGOOD</sub>	0.38	0.47	0.56	V	
Discharge ON resistor	R <sub>ON_GOOD</sub>	-	50	150	$\Omega$	
<b>[BOOT Diode]</b>						
VF voltage	V <sub>F</sub>	0.4	0.5	0.6	V	I <sub>F</sub> =1mA

○ PHYSICAL DIMENSIONS

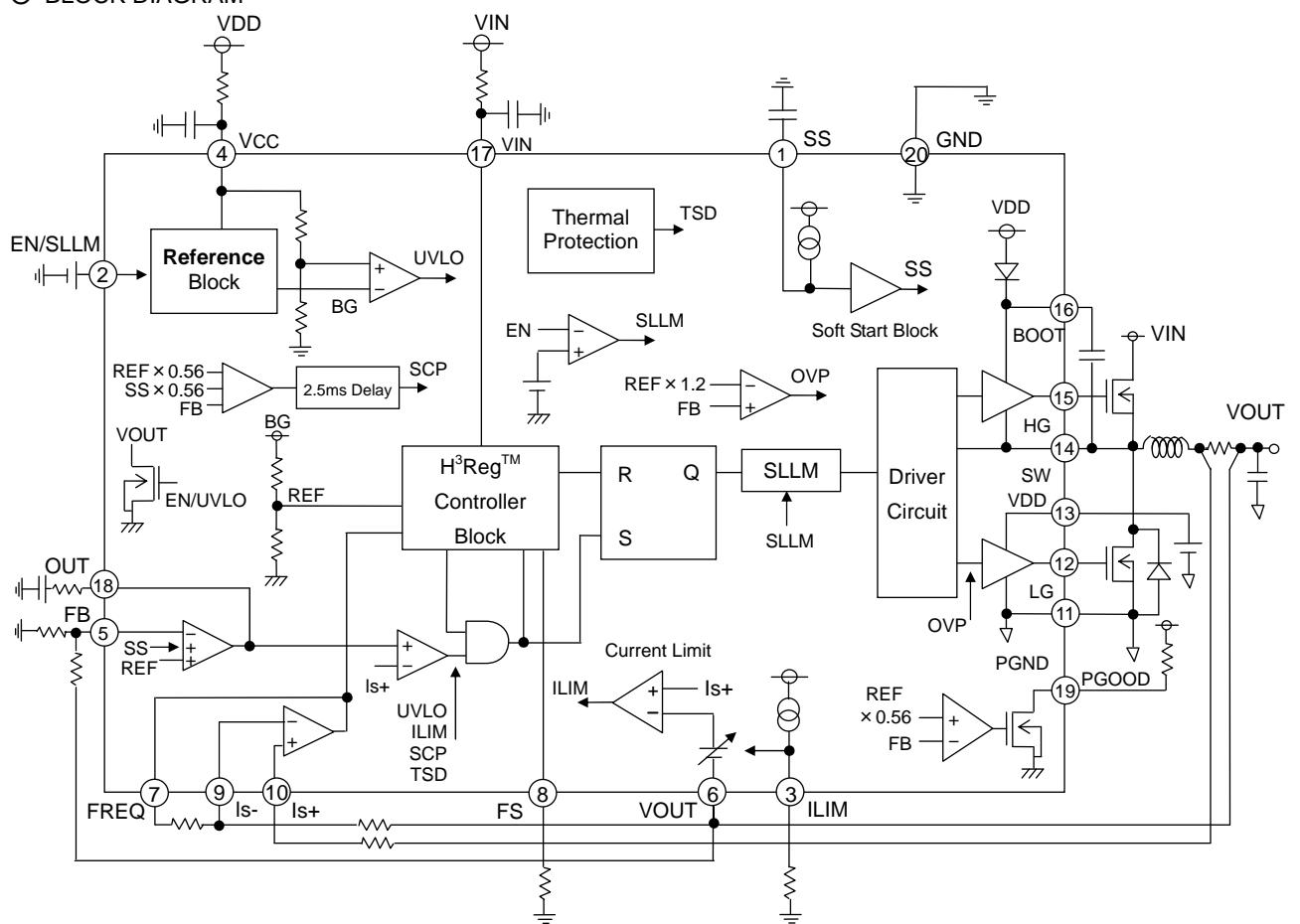


○ Pin Number Pin Name

Pin number	PIN name
1	SS
2	EN/SLLM
3	ILIM
4	VCC
5	FB
6	VOUT
7	FREQ
8	FS
9	Is-
10	Is+
11	PGND
12	LG
13	VDD
14	SW
15	HG
16	BOOT
17	VIN
18	OUT
19	PGOOD
20	GND
reverse	FIN

Please connect FIN to GND.

○ BLOCK DIAGRAM



## ● Operation Notes

### 1. Absolute maximum ratings

An excess in the absolute maximum ratings, such as supply voltage, temperature range of operating conditions, etc., can break down the devices, thus making impossible to identify breaking mode, such as a short circuit or an open circuit. If any over rated values will expect to exceed the absolute maximum ratings, consider adding circuit protection devices, such as fuses.

### 2. Connecting the power supply connector backward

Connecting of the power supply in reverse polarity can damage IC. Take precautions when connecting the power supply lines. An external direction diode can be added.

### 3. Power supply lines

Design PCB layout pattern to provide low impedance GND and supply lines. To obtain a low noise ground and supply line, separate the ground section and supply lines of the digital and analog blocks. Furthermore, for all power supply terminals to ICs, connect a capacitor between the power supply and the GND terminal. When applying electrolytic capacitors in the circuit, note that capacitance characteristic values are reduced at low temperatures.

### 4. GND voltage

The potential of GND pin must be minimum potential in all operating conditions.

### 5. Thermal design

Use a thermal design that allows for a sufficient margin in light of the power dissipation (Pd) in actual operating conditions.

### 6. Inter-pin shorts and mounting errors

Use caution when positioning the IC for mounting on printed circuit boards. The IC may be damaged if there is any connection error or if pins are shorted together.

### 7. Actions in strong electromagnetic field

Use caution when using the IC in the presence of a strong electromagnetic field as doing so may cause the IC to malfunction.

### 8. ASO

When using the IC, set the output transistor so that it does not exceed absolute maximum ratings or ASO.

### 9. Thermal shutdown circuit

The IC incorporates a built-in thermal shutdown circuit (TSD circuit). The thermal shutdown circuit (TSD circuit) is designed only to shut the IC off to prevent thermal runaway. It is not designed to protect the IC or guarantee its operation. Do not continue to use the IC after operating this circuit or use the IC in an environment where the operation of this circuit is assumed.

	TSD on temperature [°C] (typ.)	Hysteresis temperature [°C](typ.)
BD95371MUV	175	15

### 10. Ground Wiring Pattern

When using both small signal and large current GND patterns, it is recommended to isolate the two ground patterns, placing a single ground point at the ground potential of application so that the pattern wiring resistance and voltage variations caused by large currents do not cause variations in the small signal ground voltage. Be careful not to change the GND wiring pattern of any external components, either.

### 11. Heat sink (FIN)

Since the heat sink (FIN) is connected with the Sub, short it to the GND.

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